

SPECIFICATION AMENDMENTS:

Please amend the specification as follows:

Page 1, line 2, through line 8, please amend the current paragraph as follows:

--The rights of priority are claimed under 35 USC §119 of U.S. Provisional Application No. 60/413,948, filed September 27, 2002.

FIELD OF THE INVENTION

The present invention relates to a photoresist applying device and applying method therefor for applying photoresist onto a semiconductor substrate surface, and more particularly to a photoresist applying device and applying method therefor characterized in a nozzle pipe structure.--